

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A lithographic printing plate precursor comprising a hydrophilic support having provided thereon a first layer comprising a first resin that is water-insoluble and alkali-soluble and a second layer comprising a second resin that is water-insoluble and alkali-soluble in this order and a light-heat converting agent incorporated into at least one layer of the first layer and second layer, which further comprises at least one organic solvent ~~selected from organic solvents~~ having a boiling point not less than 150°C and a dipole moment not less than 3.50 debye selected from the group consisting of N-methylpyrrolidone, N,N-dimethylacetamide and dimethylsulfoxide in an amount of from 0.5 to 5% by weight based on the total dry weight of the first layer and second layer.

2. (original): A method for the preparation of a lithographic printing plate precursor comprising applying a first layer comprising a first resin that is water-insoluble and alkali-soluble with a coating solvent containing at least one organic solvent selected from organic solvents having a boiling point not less than 150°C and a dipole moment not less than 3.50 debye and then applying a second layer comprising a second resin that is water-insoluble and alkali-soluble with a solvent having a boiling point less than 150°C that does not contain the organic

solvent having a boiling point not less than 150°C and a dipole moment not less than 3.50 debye used for the application of the first layer.

3. (new) A lithographic printing plate precursor comprising a hydrophilic support having provided thereon a first layer comprising a first resin that is water-insoluble and alkali-soluble and a second layer comprising a second resin that is water-insoluble and alkali-soluble in this order and a light-heat converting agent incorporated into at least one layer of the first layer and second layer, wherein the first layer comprises at least one organic solvent selected from organic solvents having a boiling point not less than 150 °C and a dipole moment not less than 3.50 debye in an amount of from 0.5 to 5% by weight based on the total dry weight of the first layer and second layer, and the second layer does not contain said organic solvent or solvents having a boiling point not less than 150 °C and a dipole moment not less than 3.50 debye.

4. (new): The method of claim 2, wherein the at least one organic solvent is selected from the group consisting of N-methylpyrrolidone, N,N-dimethylacetamide and dimethylsulfoxide.